

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION

[0001] This application is a divisional application of Patent Application ~~Serial~~-No. 09/541,135, filed March 31, 2000, titled "Method of Forming Scribe Line Planarization Layer[["]," issued as U.S. Patent No. 6,383,894.

[0029] Following introduction, masking material 135 is subjected to a photo-definition process. In the example shown in **Figure 4**, masking layer 135 is introduced over the structure to define ~~opening~~ openings over scribe line areas 115. The structure is then exposed to light source 145, such as an ultraviolet or other light source. The light source transforms a portion of masking material 135, the exposed portion, and ignores the non-exposed portion of masking material 135.